

T_j Control for Good Heat Dissipation in NVSU333A (U365)

1. Objective

The LEDs' light output can be affected by the heat generated from the LEDs/LED-assembled products. Also, the reliability performance can be seriously degraded, if the LEDs are operated over the absolute maximum rated junction temperature (T_j).

It is critical to design the heat dissipation performance not to exceed the T_{jmax} for NVSU333A, to deliver high reliability/performance.

This document shows the T_j evaluation results by demonstrating three heat dissipation conditions. Please use the data for reference to your thermal design.

2. T_j Calculation

T_j can be calculated by the following formula:

$$T_j = T_s + R_{thj-s} \times P_D$$

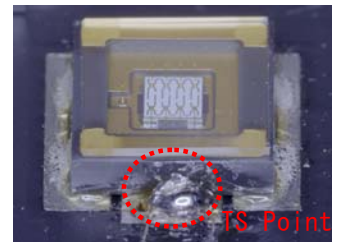
T_j: Junction Temperature

T_s: Soldering Temperature (°C)

R_{thj-s}: Thermal resistance (°C/W) from the die to the T_s measuring point

* R_{thj-s} (NVSU333A): 2.08°C/W

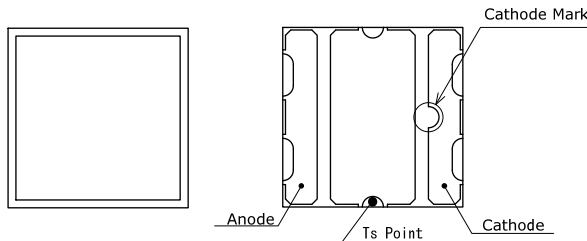
P_D: Input Power (W)



Picture 1 Ts Measuring Point

The thermocouple was solder-attached to the T_s measuring point for the evaluation.

3. T_s Measuring Point



4. T_j Evaluation Result

Example 1. Copper Board + Heat Sink B

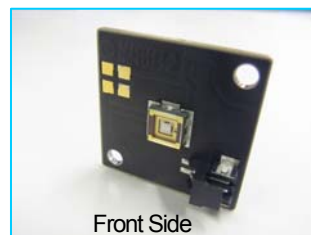
I _F (A)	T _S (°C)	V _F (V)	T _J (°C)
1.5	44.3	3.5	55
2.5	59.2	3.6	78
3.5	75.8	3.7	103

Example 2. Copper Board + Heat Sink C

I _F (A)	T _S (°C)	V _F (V)	T _J (°C)
1.5	39.4	3.6	50
2.5	50.7	3.7	70
3.5	62.9	3.8	90
4.5	75.9	3.9	112

Example 3. Copper Board + Heat Sink D

I _F (A)	T _S (°C)	V _F (V)	T _J (°C)
1.5	33.7	3.6	45
2.5	39.9	3.7	59
3.5	46.9	3.8	74
4.5	54.5	3.9	91

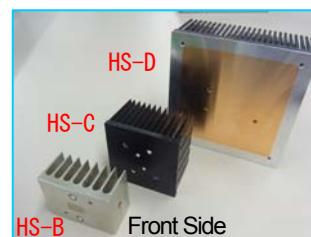


Front Side

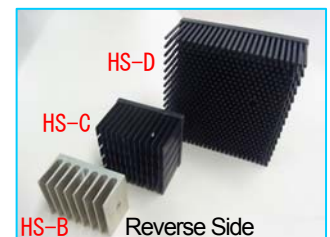


Reverse Side

Picture 2 Copper Board



Front Side



Reverse Side

Picture 3 Copper Board + Heat Sink

This sheet contains tentative information; we may change the contents without notice.

5. PCB Specifications

Type of Board	Land Pattern (μm)	Insulating Layer (μm)	Heat Conductivity (W/(m·K))	Board Thickness (mm)	Notes
Cu	35	120	10	1	The thermal pad is not in contact with the copper base.

6. Heat Dissipating Materials

Metal-based Board: Copper, 30mm × 30mm × 1.7mm

Heat Sink B: 50mm × 38mm × 25mm (H), Base Thickness: 5 mm, Fin: 8 pcs.(1mm × 38mm, Array: 1 × 8)

Heat Sink C: 54mm × 54mm × 35mm (H), Base Thickness: 4mm, Fin: 64 pcs.(0.8mm × 9mm, Array: 5 × 13)

Heat Sink D: 100mm × 100mm × 40mm (H), Base Thickness: 7mm, Fin: 707 pcs. (Φ2.1mm, Alignment; 15 × 25 / 14 × 24)

Note

We specified the absolute maximum ratings for NVSU333A; IF= 4.5A and $T_{jmax} = 100^{\circ}\text{C}$.

We cannot guarantee the usage over these ratings.

We appreciate your understanding and cooperation.